## **DECLARATION AND POWER OF ATTORNEY**

As a below named inventor, I declare that:

My residence, post office address, and citizenship are as stated below next to my name. I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first, and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled

ADDADATHS AND	METHOD FOR SUI	PPLYING CRYSTALLINE MATERIAL	S IN CTOCHOM SKI METHOR
AFFARA I US AND	MICI HOD FOR SUI	PPLIING CRISIALLINE MAIERIAL	S IN CZUCRKALSKI MF I HOI:

	the specification of which is attached her			
	was filed onamended on	as patent application	Serial No.	, and (if applicable) was
I hereby	state that I have reviewed and understand th	e contents of the above identified s	pecification, including the claims, as arr	nended by any amendment referred to
above.				
I acknov §1.56.	wledge the duty to disclose information of w	hich I am aware and which is mate	rial to the examination of the patent app	plication in accordance with 37 CFR
I hereby	claim foreign priority benefits under 35 U.:	S.C. §119(a)-(d) or §365(b) of any	y foreign application(s) for patent or in	ventor's certificate, or §365(a) of any
	ernational application which designates at lea ign application for patent or inventor's certif			
Prior F	oreign Application(s)	•		
	Number	Country	Day/Month/Year Filed	Priority Not Claimed
	2003-138337	JAPAN	16/05/2003	
	2000 100001		10/00/2000	
Y hamahı	claim the benefit under 35 U.S.C. §119(e) o	f any United States provinional and	liantian(a) listed below	
тпасоу			•	•
	Application Serial Num	ber	Filing Date	
	claim the benefit under 35 U.S.C. §120 of all clow and, insofar as the subject matter of each			
the man	ner provided by the first paragraph of 35 U.S	S.C. §112, I acknowledge the duty	to disclose information known to me w	hich is material to the patentability as
defined	in 37 CFR §1.56 which became available be	tween the filing date of the prior ap	plication and the national or PCT intern	ational filing date of this application.
	Application Serial Number	Filing Date	Status (patented, pending,	abandoned)
			-	
F1	design of a stimute base of the CONTR	AD T CHAPT OF LAND Y	20.240) I CHTDYCMONYIOD IV	DRODY CD 14 14 N 22 (12)
	ndersigned applicant hereby appoints CONR ttorneys with full power of substitution to th.			
	orrespondence to: CLARK & BRODY, 1	750 K Street, NW, Suite 600, W	ashington, DC 20006; Telephone:	202-835-1111; Facsimile: 202-835-
	declare that all statements made herein of my or	wn knowledge are true and that all sta	tement made on information and belief are	believed to be true; and further that there
	ts were made with the knowledge that willful fal			concrete to be due. and fulled that these
WT ". 10				
United S	tates Code and that such willful false statements			
		may jeopardize the validity of the appl		
Full na	me of sole or first inventor:	may jeopardize the validity of the appl Katsunori NAKASHIMA	lication or any patent issued thereon.	oth, under Section 1001 of Title 18 of the
Full na	nme of sole or first inventor: or's signature:	may jeopardize the validity of the appl	lication or any patent issued thereon.	
Full na	nme of sole or first inventor: or's signature: <i>Katsure</i> ence:Tokyo, Japan	may jeopardize the validity of the appl Katsunori NAKASHIMA	lication or any patent issued thereon.	oth, under Section 1001 of Title 18 of the
Full na Invent Reside Citizer	nme of sole or first inventor:  or's signature:  nce:  Tokyo, Japan  ship:  Japan	may jeopardize the validity of the appl Katsunori NAKASHIMA LOUI Nakashima	lication or any patent issued thereon.	oth, under Section 1001 of Title 18 of the
Full na Invent Reside Citizer Post C	nme of sole or first inventor:  or's signature:  nce:  Tokyo, Japan  ship:  Japan	may jeopardize the validity of the appl Katsunori NAKASHIMA LOUI Nakashima	ication or any patent issued thereon.  Date:	oth, under Section 1001 of Title 18 of the
Full na Invento Reside Citizer Post C	ame of sole or first inventor:  or's signature:  Tokyo, Japan  iship:  Japan  office Address:  c/o Sumitomo Mit	may jeopardize the validity of the appl Katsunori NAKASHIMA LOVI Nakashim a subishi Silicon Corporation, 2	Date:	oth, under Section 1001 of Title 18 of the
Full na Invento Reside Citizer Post C	time of sole or first inventor:  or's signature:  Tokyo, Japan  iship:  Japan  office Address:  c/o Sumitomo Mit  ame of second joint inventor, if any:  or's signature:  Tats	may jeopardize the validity of the appl Katsunori NAKASHIMA LOVI Nakashim a subishi Silicon Corporation, 2	ication or any patent issued thereon.  Date:	oth, under Section 1001 of Title 18 of the
Full na Invente Reside Citizer Post C Full na Invente Reside Citizer	arme of sole or first inventor:  or's signature:  Tokyo, Japan  office Address:  or's signature:  Japan  office Address:  or's signature:  Tokyo, Japan  or's signature:  Tokyo, Japan  orship:  Japan	may jeopardize the validity of the apple  Katsunori NAKASHIMA  LOVE Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAYA YABUSAME	Date: Date: Date: Date:	oth, under Section 1001 of Title 18 of the 6 /03 /2004  Tokyo 105-8634 Japan
Full na Invente Reside Citizer Post C Full na Invente Reside Citizer	arme of sole or first inventor:  or's signature:  Tokyo, Japan  office Address:  or's signature:  Japan  office Address:  or's signature:  Tokyo, Japan  or's signature:  Tokyo, Japan  orship:  Japan	may jeopardize the validity of the apple  Katsunori NAKASHIMA  LOVE Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAYA YABUSAME	Date:	oth, under Section 1001 of Title 18 of the 6 /03 /2004  Tokyo 105-8634 Japan
Full na Invente Reside Citizer Post C Full na Invente Reside Citizer Post C	arme of sole or first inventor:  or's signature:  Tokyo, Japan  office Address:  or's signature:  Japan  office Address:  Tokyo, Japan  or's signature:  Tokyo, Japan  office Address:  Tokyo, Japan  office Address:  Office Addre	may jeopardize the validity of the apple  Katsunori NAKASHIMA  LOVE Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAYA YABUSAME	Date: Date: Date: Date:	oth, under Section 1001 of Title 18 of the 6 /03 /2004  Tokyo 105-8634 Japan
Full na Inventor Reside Citizer Post Control Full na Inventor Reside Citizer Post Control Full na Full	ame of sole or first inventor:  or's signature:  Tokyo, Japan  Office Address:  or's signature:  Tokyo, Japan  Office Address:  Tokyo, Japan  Office:  Tokyo, Japan  Office Address:  Tokyo, Japan	may jeopardize the validity of the application in NAKASHIMA  LOCI Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAY Yabusame  ubishi Silicon Corporation, 2-1	Date:	th, under Section 1001 of Title 18 of the 6 / 03 / 2004  Tokyo 105-8634 Japan  Tokyo 105-8634 Japan
Full na Inventor Reside Citizer Post Control Full na Inventor Reside Citizer Post Control Full na Full	arme of sole or first inventor:  or's signature:  Tokyo, Japan  Office Address:  or's signature:  Tokyo, Japan  or's signature:  Tokyo, Japan  Office Address:  Tokyo, Japan  Office Addre	may jeopardize the validity of the application in NAKASHIMA  LOCI Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAY Yabusame  ubishi Silicon Corporation, 2-1	Date: Date: Date: Date:	th, under Section 1001 of Title 18 of the 6 / 03 / 2004  Tokyo 105-8634 Japan  Tokyo 105-8634 Japan
Full na Invention Post Continuent Reside Citizer Post Continuent Reside Citizer Post Continuent Reside Citizer Reside Citizer	arme of sole or first inventor:  por's signature:  Tokyo, Japan  Inship:  Japan  Iffice Address:  Tokyo, Japan	may jeopardize the validity of the application in NAKASHIMA  LOCI Nakashima  subishi Silicon Corporation, 2  Tatsuya YABUSAME  WAY Yabusame  ubishi Silicon Corporation, 2-1	Date:	th, under Section 1001 of Title 18 of the 6 / 03 / 2004  Tokyo 105-8634 Japan  Tokyo 105-8634 Japan